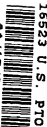


09/15/03



16523 U.S. PTO

UTILITY APPLICATION

Attorney Docket No.: MICRON.241DV1
First Named Inventor: Paul A. Farrar
Title: MULTIPLE CHIP STACK STRUCTURE AND
COOLING SYSTEM
Express Mail Label No.: EV 308 021 340 US

Direct all correspondence to Customer No.: 20995Date: September 12,
2003

Page 1 of 2

Mail Stop Patent Application

United States Patent and Trademark Office
PO Box 1450
Alexandria, VA 22313-1450

22151 U.S. PTO
10/662828
09/15/03

The following enclosures are transmitted herewith to be filed in the patent application of:

Inventor(s):

1. Paul A. Farrar
2. Jerome M. Eldridge
- 3.
- 4.

APPLICATION ELEMENTS:

- (X) Specification in 20 pages.
- (X) Drawings in 8 sheets.
- (X) Declaration by Inventors in pages.
 - Copy from parent application
 - Incorporation by Reference. The entire disclosure of the prior application, from which a copy of the oath or declaration is supplied, is considered a part of the disclosure of the accompanying application and is hereby incorporated by reference therein.
 - Examiner in prior application: Jasmine Clark
 - Group Art Unit of prior application: 2815

CONTINUITY INFORMATION:

- (X) This application is a divisional application of U.S. Patent Application No. 09/945,042 filed August 31, 2001 and is also related to co-pending U.S. Patent Application No. 09/945,024, filed August 30, 2001.
- (X) Incorporation by Reference. The entire disclosure of the prior application(s) is considered a part of the disclosure of the accompanying application and is hereby incorporated by reference therein.

OTHER APPLICATION PARTS:

- (X) Return prepaid postcard.

UTILITY APPLICATION

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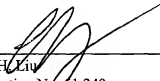
Page 2 of 2

FILING FEES:

| FEE CALCULATION | | | | |
|--------------------|-------------|--------------|----------------------|--------------|
| FEE TYPE | | FEE CODE | CALCULATION | TOTAL |
| Basic Utility | | 1001 (\$750) | | \$750 |
| Non-English Spec. | | 1053 (\$130) | | \$0 |
| Recordation Fee | | 8021 (\$40) | 0 x 40 = | \$0 |
| Excess Claims > 20 | 13 - 20 = 0 | 1202 (\$18) | 0 x 18 = | \$0 |
| Independent > 3 | 2 - 3 = 0 | 1201 (\$84) | 0 x 84 = | \$0 |
| Multiple Claim | | 1203 (\$280) | | \$0 |
| | | | TOTAL FEE DUE | \$750 |

(X) A check in the amount of \$750 to cover the Total Fee Due is enclosed.

The Commissioner is hereby authorized to charge any additional fees which may be required, now or in the future, or credit any overpayment to Account No. 11-1410.



Linda H. Liu
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MAIL STOP PATENT APPLICATION

Commissioner for Patents

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CERTIFICATE OF MAILING BY "EXPRESS MAIL"

Attorney Docket No. : MICRON.241DV1

Applicant(s) : Paul A. Farrar and Jerome M. Eldridge

For : MULTIPLE CHIP STACK STRUCTURE
AND COOLING SYSTEM

Attorney : Linda H. Liu

"Express Mail"

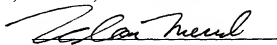
Mailing Label No. : EV 308 021 340 US

Date of Deposit : September 15, 2003

I hereby certify that the accompanying

Transmittal letter; specification in 20 pages; 8 sheets of drawings; copy of
SIGNED Declaration from parent application in 2 pages; Check(s) for Filing
Fee(s); Return Prepaid Postcard

are being deposited with the United States Postal Service "Express Mail Post Office to Addressee" service under 37 CFR 1.10 on the date indicated above and are addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.



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